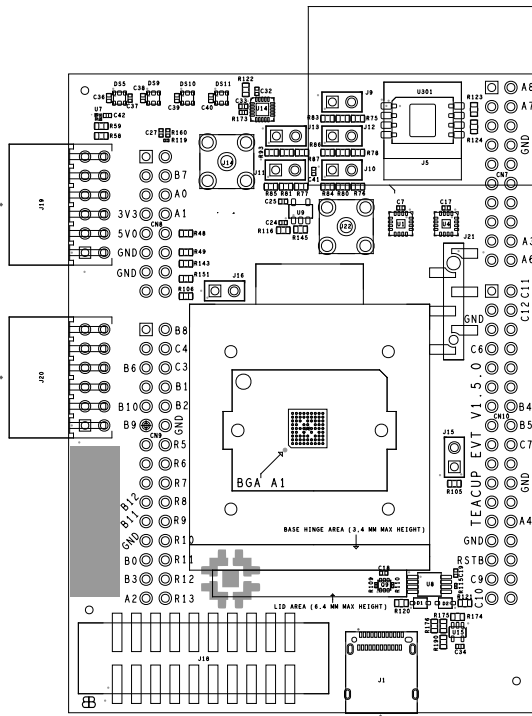



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1.3.0	INITIAL	11/22/23	BBLEKER
1.4.0	CHANGED ASSEMBLY NPTE WITH G650 P/N	11/27/23	BBLEKER
1.5.0	EVT UPREV WITH BUG AND DESIGN FIX	04/11/24	BBLEKER



HYP_OT
SILKSCREEN TOP
ASSEMBLY DRAWING TOP

NOTES: UNLESS OTHERWISE SPECIFIED.

- INTERPRET DRAWING PER ASME Y14.100
- WORKMANSHIP SHALL BE EQUAL TO AND COMPLIANT WITH THE REQUIREMENTS OF IPC-A-610, LATEST REVISION.
- STAMP OR LABEL ASSEMBLY PN: TEACUP EVT V1.5.0 WITH CONTRASTING COLOR INK IN THE LOCATION INDICATED. BARCODE HEIGHT SHALL BE 5 MM MINIMUM.
- ESD SHIELDING BAGS SHALL BE PLACED IN OVER-PACK CONTAINERS THAT PROVIDE ADEQUATE PROTECTION FOR SAFE TRANSPORTATION AND STORAGE. OVER-PACK CONTAINERS TO BE IDENTIFIED WITH ESD WARNING LABELS.
- DESIGNATION ARE FOR REFERENCE ONLY AND DO NOT APPEAR ON INDIVIDUAL PARTS.
- USE NO-CLEAN PROCESS. AQUEOUS CLEANING IS PROHIBITED.
- MARK THE BILL OF MATERIALS REVISION IN THE AREA SHOWN. BAG AND TAG ACCEPTABLE FOR ASSEMBLIES THAT ARE TOO SMALL OR TOO DENSE FOR STANDARD LABELING.
- THIS ASSEMBLY DRAWING MAY SHOW COMPONENT LOCATIONS THAT ARE NO-STUFF OPTIONS. REFER TO THE SPECIFIC BILL OF MATERIALS (BOM) FOR COMPONENTS USED IN EACH BOARD OPTION.
- PRINTED CIRCUIT BOARD ASSEMBLY PROCESS AND MATERIALS USED MUST BE COMPLIANT WITH THE RESTRICTION ON USE OF HAZARDOUS SUBSTANCES (RoHS) DIRECTIVE.

UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES ARE IN mm	SIGNATURES		DATE					
	DRAWN	BRENDAN BLEKER	04/11/24		ASSEMBLY DRAWING OpenTitan Hyperdebug Shield (TEACUP)			
	DESIGNER	BRENDAN BLEKER	04/11/24					
	CHECKER	BRENDAN BLEKER	04/11/24		SIZE D	FSCM NO	DWG NO EVT-150-ASD	REV
	QA	XXXXXXXX	XX/XX/XX					EVT 1.5.0
	ENGRG	BRENDAN BLEKER	04/11/24					SCALE NONE
	ISSUED		04/11/24					

